

S/N 10/786,354



PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Kie Y. Ahn et al. Examiner: Andy Huynh  
Serial No.: 10/786,354 Group Art Unit: 2818  
Filed: February 25, 2004 Docket: 303.686US3  
Title: MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS  
AND AIR GAPS

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**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), Applicants request that the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p) be charged to Deposit Account No. 19-0743.

06/21/2005 ZJUHAR1 00000023 190743 10786354

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Page 2  
Dkt: 303.686US3

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
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(612) 349-9587

Date

15 June '05

By

Timothy B Clise  
Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 16 day of June, 2005.

Judy Dent

Name

Signature

Judy Dent

Substitute for form 1449A/PTO <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> (Use as many sheets as necessary)		<i>Complete if Known</i>	
		<b>Application Number</b>	10/786,354
		<b>Filing Date</b>	February 25, 2004
		<b>First Named Inventor</b>	Ahn, Kie
		<b>Group Art Unit</b>	2818
		<b>Examiner Name</b>	Huynh, Andy
Sheet 1 of 1		Attorney Docket No: 303.686US3	

*O I P E JUN 20 2005*  
*PATENT & TRADEMARK OFFICE*

**US PATENT DOCUMENTS**

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
	US-5,953,626	09/14/1999	Hause, F. N., et al.	06/05/1996
	US-6,342,722	01/29/2002	Armacost, M., et al.	08/05/1999
	US-6,413,827	07/02/2002	Farrar, Paul A.	02/14/2000
	US-6,633,074	10/14/2003	Ahn, K. Y.	06/03/1999

**FOREIGN PATENT DOCUMENTS**

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T <sup>2</sup>

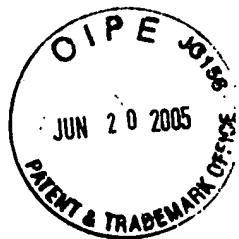
**OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>

**EXAMINER****DATE CONSIDERED**

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Applicant: Kie Y. Ahn et al.  
Title: MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS AND AIR GAPS  
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Examiner: Andy Huynh



Serial No.: 10/786,354  
Due Date: N/A  
Group Art Unit: 2818

**MS Amendment**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

A return postcard.  
 A Supplemental Information Disclosure Statement (2 pgs.), and Form 1449 (1 pg.) Documents NOT enclosed.  
 A check in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
Customer Number 21186

By:   
Atty: Timothy B. Clise  
Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 16<sup>th</sup> day of June, 2005.

Name

Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)



Receipt is hereby acknowledged for the following in the United States Patent and  
Trademark Office:

In re Patent Application of: Kie Y. Ahn et al.

Title: MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS  
AND AIR GAPS

Serial No.: 10/786,354

Filing Date: February 25, 2004

CONTENTS: An Supplemental Information Disclosure Statement (2 pgs.),  
Form 1449 (1 pg.), Return Postcard and Transmittal Sheet.

Mailed: June 16, 2005  
TBC/jld

Docket No.: 303.686US3  
Due Date: N/A